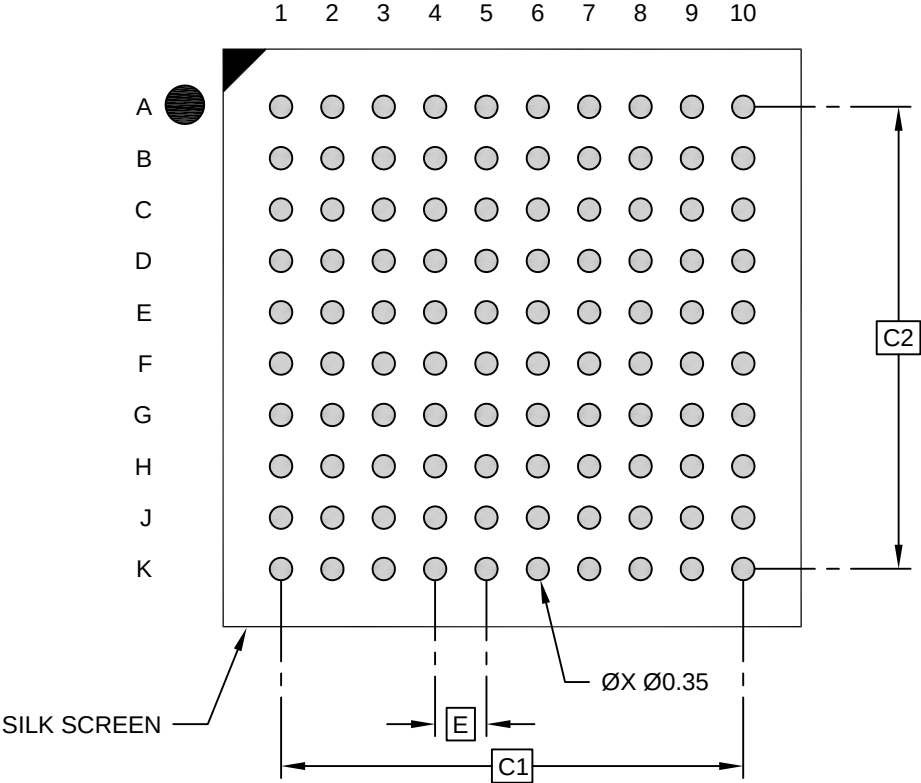


100-Ball Ceramic Ball Grid Array Package (A3B) - 9x9 mm Body [CBGA]
Atmel Legacy Global Package Code CPR

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.58 BSC		
Overall Pitch	C1	7.20 BSC		
Contact Pad Spacing	C2	7.20 BSC		
Contact Pad Diameter (X100)	X1			0.35

- Notes:
- 1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - 2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process